Features

- FET SP2T Absorptive design
- Frequency: DC-20GHz
- Isolation: 45dB Typical
- Insertion Loss: 2.0dB Typical
- Control Voltage: 0/-5V
- Switching Speed: 10ns Typical
- Die Size: 1.55 x 1.4 x 0.1 mm

Typical Applications

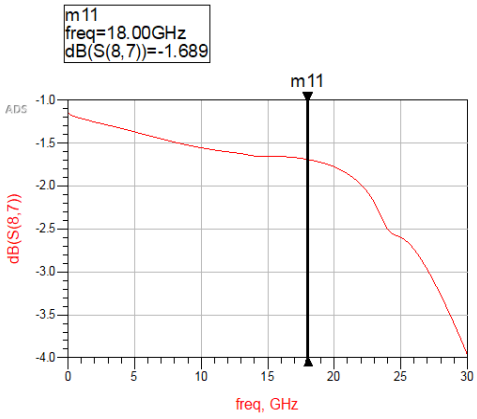
- Voltage control
- Fast Switching Speed
- Low Insertion Loss and High Isolation
- Customization available upon request

Electrical Specifications

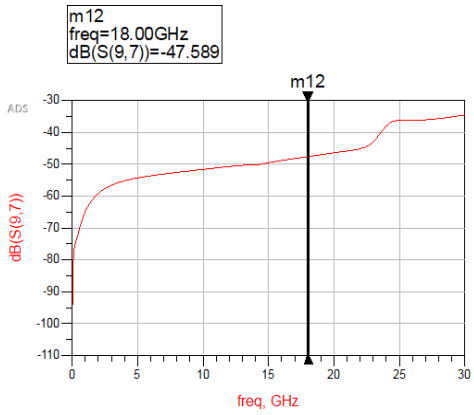
TA = +25°C, VCTL=0/-5V

Parameters	Min.	Typ.	Max.	Units
Frequency	**DC**		**20**	**GHz**
Insertion Loss		**2.0**	**2.5**	**dB**
Isolation	**40**	**45**		**dB**
Input VSWR			**1.5**	**:1**
Output VSWR			**1.5**	**:1**
P1dB - Output 1dB Compression	**20**	**23**		**dBm**
IIP3-Input Third Order Intercept		**-**		**dBm**
Switching Speed		**10**		**ns**

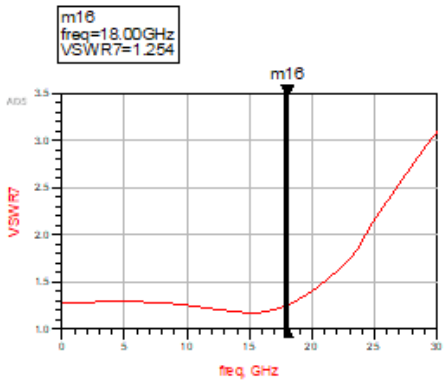
Insertion Loss vs. Frequency



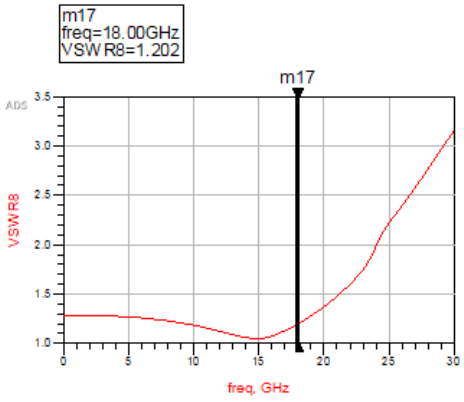
Isolation vs. Frequency



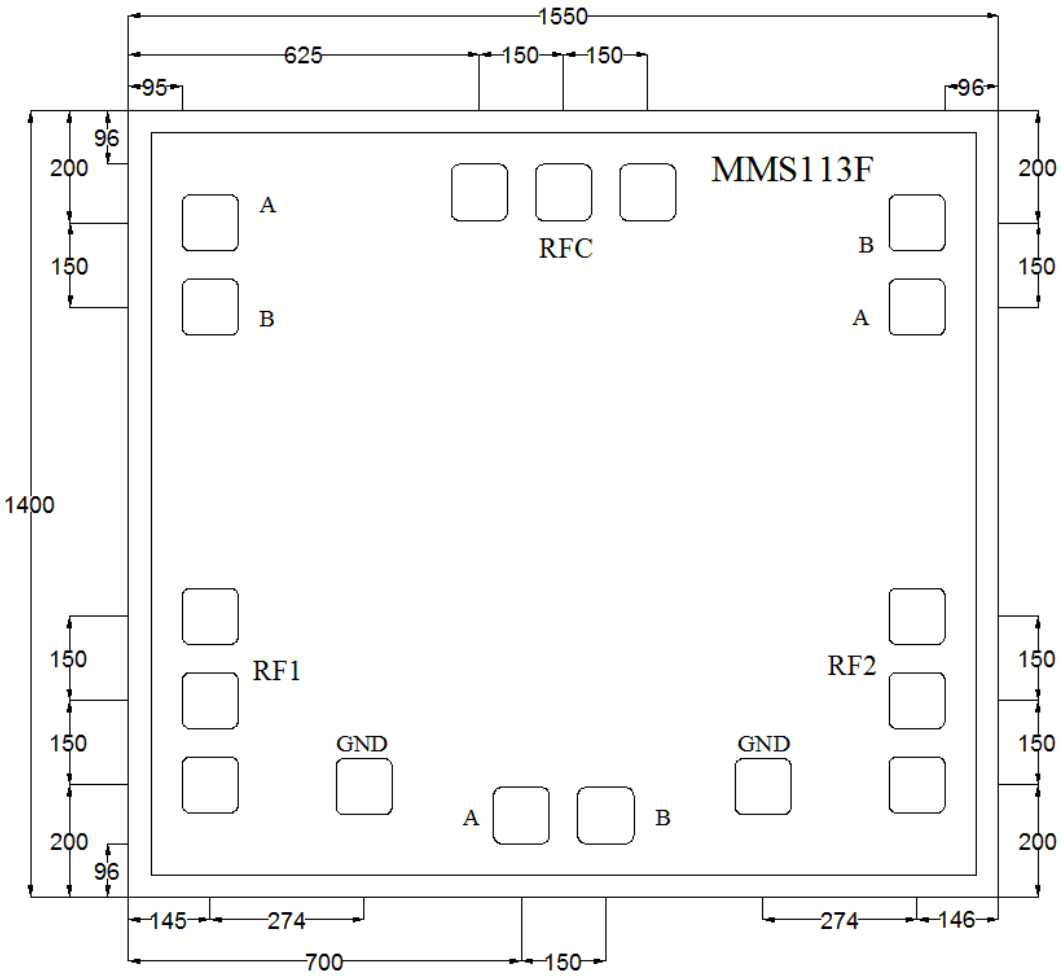
Input VSWR vs. Frequency



Output VSWR vs. Frequency



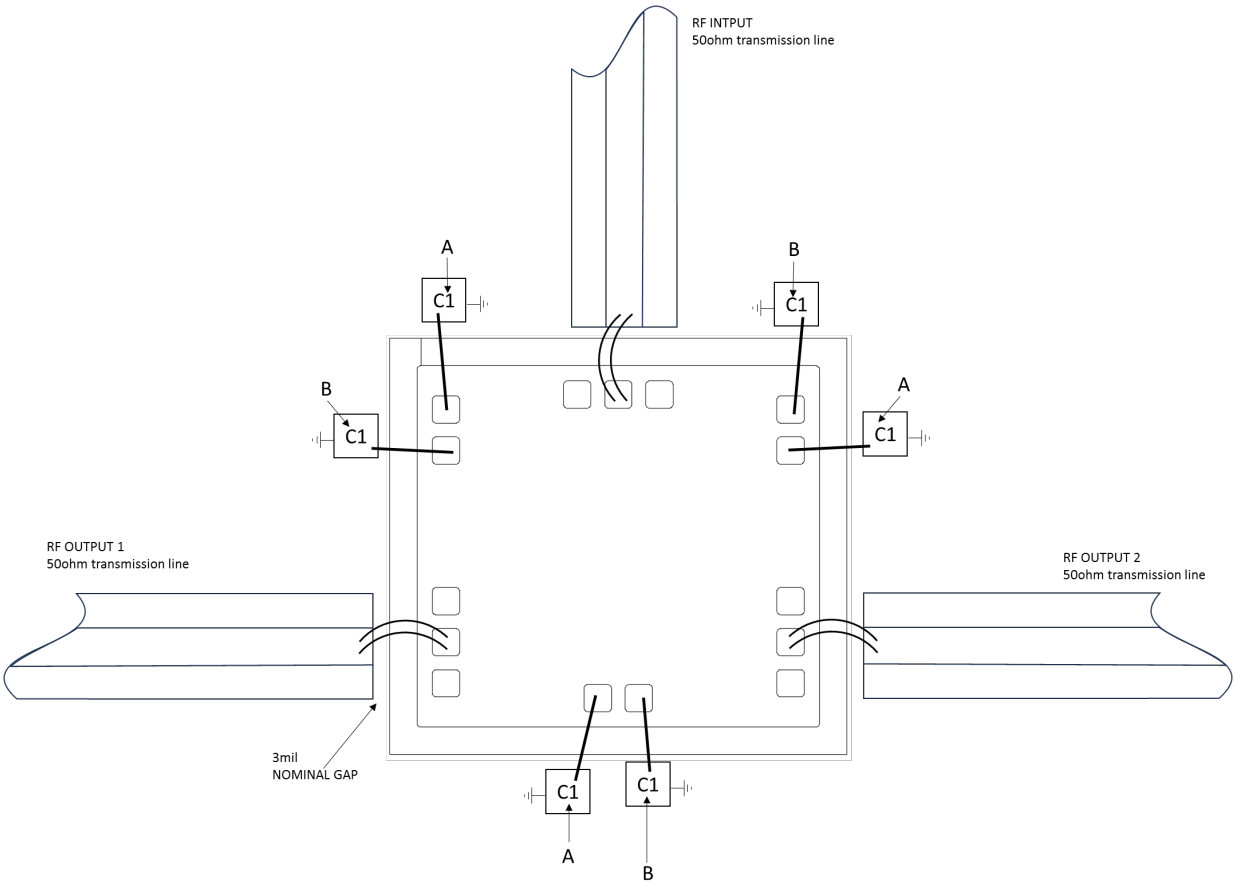
Outline Drawing:
All Dimensions in µm



Truth Table

Control Voltage		State	
A	B	RF1	RF2
-5V	0V	ON	OFF
0V	-5V	OFF	ON

Assembly Drawing



Notes:

1. **Die thickness:100µm**
2. **Typical bond pad is 100*100µm²**
3. **Bond pad mentalization: Gold**
4. **Backside metallization: Gold**
5. **Backside of the die (GND)**
6. **No connection required for unlabeled bond pads**

Item	Description
C1	39pF Capacitor Example: Skyworks Part: SC10002430